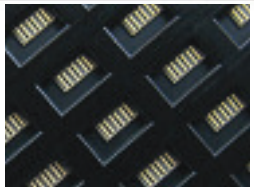
For RF Noise Suppression in high speed mixed signal semiconductor devices



Miniature RF Blocking Network

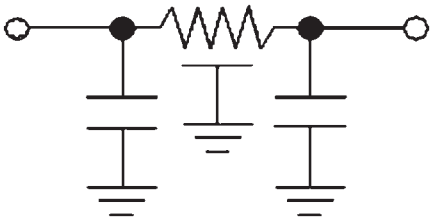
Functional Applications:

- High Speed Digital
- Mixed Signal IC's
- Suppression of Noise on DC Supply Lines
- MCM and Hybrid Modules

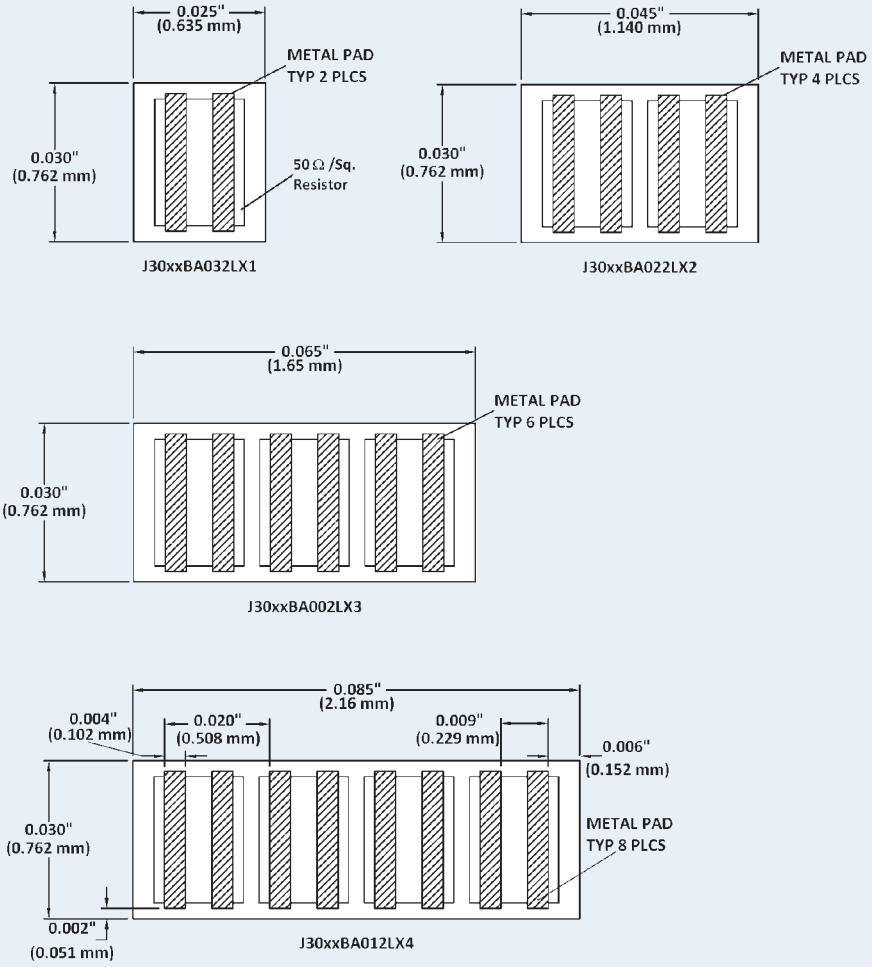
Benefits:

- Eliminates Noise at I/O Pins
- Replaces Large Decoupling Capacitor with Superior Performance
- Clean DC Lines Beyond 18 GHz

Segment Equivalent Schematic Representation



Layout and Dimensions



Part Number Identification

J	30	XX	BA01	2	L	X	4
Product J = Blocking Network	**Width** (Mils)	**Material** BL or BJ	**Internal Drawing Reference**	**Voltage** 2 = 25 Vdc	**Metallization** 100µ" Gold Finish	**Test Level** Commercial	**Number of RC Segments**

Material and Electrical Characteristics

Material Code	Capacitance (typical)	Resistance (pad to pad)	DF	TCC	Rated Voltage
BL	30 pF	10Ω Nom.	3.0% Max.	X7R	25 Vdc
BJ	45 pF	10Ω Nom.	3.0% Max.	X7R	25 Vdc

Miniature RF Blocking Network

Metallization:

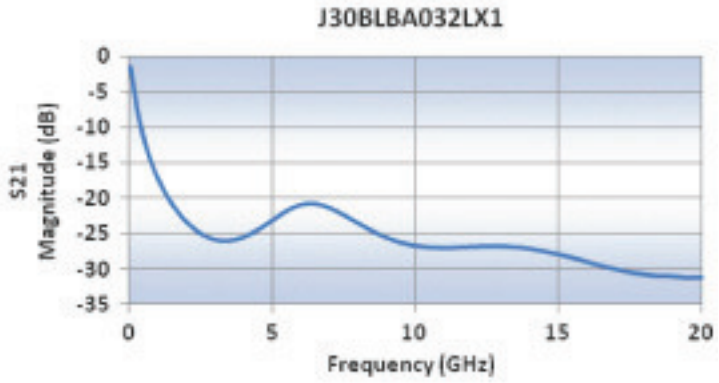
Top: 50•/Square TaN, 300Å TiW, 100 • Inch minimum Au.

Bottom: 300Å TiW, 100 • Inch minimum Au.

Screening Options

Test Code	Test/Inspection	Sample Size	Description
X	Bond Strength	2 Pcs/Plate	2 bonding pads on each sample
	IR	1% AQL	2 1/2 times rated voltage of 25 volts
	Visual Inspection	100%	4 Side visual screening
	Pad to pad resistance check	1% AQL	Ensure isolation between segments and boarder

Performance



Segment Bonding for Measurement



For additional data of multi-segment devices please contact an inside sales representative.

Typical Application

